

ABSTRACT OF THE DISCLOSURE

A transfer sheet of the present invention includes a resin film having a glass transition temperature of not lower than 60°C, a silicone resin layer formed on the resin film, and a metal wiring pattern formed on the silicone resin layer. The metal wiring pattern has an exposed face that forms a roughened face, and the roughened face has a ten-point average surface roughness (Rz) of 2 μm or more, while a face of the wiring pattern, which is in contact with the silicone resin layer, has a surface roughness (Rz) lower than that of the exposed face. Thereby, the present invention provides a transfer sheet that has improved transfer performance for enabling transferring at low temperature, and improved dimensional stability and also a via-connection reliability. The present invention provides also a wiring board using the transfer sheet and a method of manufacturing the same.

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